

Call for Papers

Special Issue on Electrets and Related Phenomena

A special issue of the IEEE Transactions on Dielectrics and Electrical Insulation (IEEE TDEI) is being planned on Electrets and Related Phenomena for publication in June 2024. This issue is open to all authors. Presenters of papers at the IEEE 19th International Symposium on Electrets (ISE19) to be held during September 18-22, 2023 in Linz (Austria) are especially encouraged to submit their work to this special issue.

Authors are invited to submit their manuscripts to the IEEE TDEI submission portal <https://ieee.atyponrex.com/journal/tdei>. During the first step of the submission process, authors will be able to choose the name of the intended special issue. Instructions for preparation of manuscripts and templates for MSWord and LaTeX are available at <https://ieeedeis.org/publications/transactions-on-dielectrics-and-electrical-insulation/>.

For this special issue suggested topics include, but are not limited to:

- Charge related phenomena in dielectrics (charge injection, transport & trapping)
- Thermally stimulated current & dielectric relaxation
- Nanoscale measurements of electrostatic phenomena
- Ferroelectric, piezoelectric & pyroelectric phenomena
- Ferroelectrets & photoelectrets
- Electrostatic & dielectric phenomena in life science: bioelectrets
- Non-linear electrical & optical effects
- Applications of thin-film ferroelectric materials
- Electrets in organic electronics
- Soft actuators & sensors
- Functional materials and dielectrics

In accordance with IEEE policy, papers that have been published in any conference proceedings cannot be republished. A plagiarism tool will be used to verify originality. Submissions will undergo full peer review by at least two reviewers. Accepted papers will be available online within 10 days as Early view papers in IEEE Xplore.

The deadline for the submission of the manuscripts is November 30, 2023. Further questions concerning this Special Issue could be directed to either one of the three Guest Editors or directly to the Editor-in-Chief of the *IEEE Transaction on Dielectrics and Electrical Insulation*, Professor Michael Wübbenhorst (wubbenhorst@kuleuven.be). The Guest Editors for this special issue are:

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